

HS 3120 Data Converter Line

Double Buffered 12-Bit MDAC

FEATURES

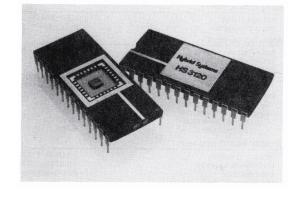
- Monolithic Construction
- 12-Bit Resolution
- 0.01% Non-Linearity
- jup Compatible
- 4-Quadrant Multiplication
- Latch-up Protected

DESCRIPTION

The HS 3120 is a precision monolithic 12-bit multiplying DAC with internal two-stage input storage registers for easy interfacing with microprocessor busses. It is packaged in a 28-pin DIP to give high I/O design flexibility.

DOUBLE BUFFERED—The input registers are sectioned into 3 segments of 4 bits each, all individually addressable. The DAC register, following the input registers, is a parallel 12-bit register for holding the DAC data while the input registers are updated. Only the data held in the DAC register determines the analog output value of the converter.

MICRO PROCESSOR COMPATIBLE — The HS 3120 has been designed for great flexibility in connecting to bus-oriented systems. The 12 data inputs are organized into 3 independent addressable 4-bit input registers such that the HS 3120 can be connected to either a 4, 8 or 16-bit data bus. The control logic of the HS 3120 includes chip enable and latch enable inputs for flexible memory mapping. All

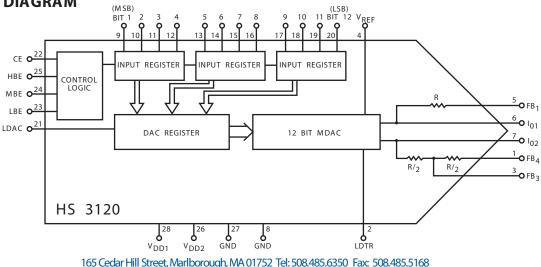


controls are level-triggered to allow static or dynamic operation.

VERSATILE OUTPUTS — A total of 5 output lines are provided by the HS 3120 to allow unipolar and bipolar output connection with a minimum of external components. The feedback resistor is internal. The resistor ladder network termination is externally available, thus eliminating an external resistor for the 1 LSB offset in bipolar mode.

MONOLITHIC CMOS CONSTRUCTION — The HS 3120 is a one-chip CMOS circuit with a resistor ladder network designed for 0.01% linearity without laser trimming. Small chip size and high manufacturing yields result in greatly reduced cost.

FUNCTIONAL DIAGRAM



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SPECIFICATIONS (Typical @ 25°C, nominal power supply, V_{REF}=+10V, unipolar unless otherwise noted).

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Digital input voltage must not exceed supply voltage or go below -0.5V. "0" <0.8V, 2.4V < "1" VDD
All strobes are level triggered. See TIMING DIAGRAM.
Using the internal feedback resistor and an external opamp.
The output leakage current will create an offset voltage at the external opamps output. It doubles every 10°C temperature increase.
Delay times are twice the amount shown at TA =+125°C

PIN ASSIGNMENTS

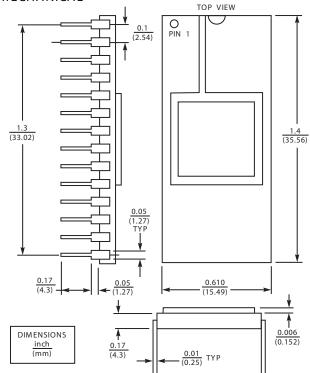
PIN	FUNCTION
1	FB ₄ , Feedback Bipolar Operation
2	LDTR, Ladder Termination
3	FB ₃ , Feedback Bipolar Operation
4	V _{REF} Reference Voltage Input
5	FB ₁ , Feedback, Unipolar/Bipolar
6	l ₀₁ , Current out into virtual ground
7	I ₀₂ , Current out-complement of I ₀₁
8	V _{SS} , Ground, Analog and DAC Register
9	Bit 1,MSB
10	Bit 2
11	Bit 3
12	Bit 4
13	Bit 5
14	Bit 6
15	Bit 7
16	Bit 8
17	Bit 9
18	Bit 10
19	Bit 11
20	Bit 12
21	LDAC, Transfers data from input to DAC register
22	CE, Chip Enable, active low
23	LBE, Bit 12 to Bit 9 Enable
24	MBE, Bit 8 to Bit 5 Enable
25	HBE, Bit 4 to Bit 1 Enable
26	V _{DD2} , Supply Analog and DAC Register
27	V _{SS1} , Ground input latches
28	V _{DD1} , Supply input latches

NOTE: Pins 8 and 27 and pins 26 and 28 must be connected externally.

ORDERING INFORMATION

MODEL	DESCRIPTION
HS 312000	Double Buffered 12-Bit MDAC. Commercial
HS 3120C-2	Double Buffered 12-Bit MDAC. Commercial
HS 3120B-0	Double Buffered 12-Bit MDAC. MIL-STD-883C
HS 3120B-2	Double Buffered 12-Bit MDAC. MIL-STD-883C

MECHANICAL



CONNECTIONS	
Unipolar Operation:	Connect I ₀₁ and FB ₁
	Tie I ₀₂ , (Pin 7). FB ₃ , (Pin 3), FB ₄ , (Pin 1)
	all to Ground (Pin 8)
Bipolar Operation:	Connect I ₀₁ , I ₀₂ , FB ₁ , FB ₃ , FB ₄
	Tie LDTR to I ₀₂
Grounding:	Connect all GRD to system analog ground
	and tie this to digital ground.
NOTE:	All unused input must be grounded

Consult factory for application information.

CAUTION: ESD (Electro-Static Discharge) sensitive device. Permanent damage may occur when unconnected devices are subjected to high energy electrostatic fields. Unused devices must be stored in conductive foam or shunts. Protective foam should be discharged to the destination socket before devices are removed. Devices should be handled at static safe workstations only. Unused digital inputs must be grounded or tied to the logic supply voltage. Unless otherwise noted, the supply voltage at any digital input should never exceed the supply voltage by more than 0.5 volts or go below -0.5 volts. If this condition cannot be maintained, limit input current on digital inputs by using series resistors or contact Hybrid Systems for technical assistance.

Specifications subject to change without notice.

